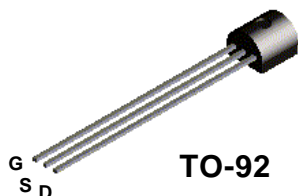


MPF102



N-Channel RF Amplifier

This device is designed for electronic switching
Applications such as low ON resistance analog switching.
Sourced from Process 50.

Absolute Maximum Ratings * TA=25 degree C unless otherwise noted

Symbol	Parameter	Value	Units
V _{DG}	Drain-Gate Voltage	25	V
V _{GS}	Gate-Source Voltage	-25	V
I _{GF}	Forward Gate Current	10	mA
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to + 155	degree C

* This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES :

- 1) These rating are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics TA = 25 degrees C unless otherwise noted.

Symbol	Characteristic	Max	Units
P _D	Total Device Dissipation	350	mW
	Derate above 25 degrees C	2.8	mW/degrees C
R _{θJC}	Thermal Resistance, Junction to Case	125	degrees C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	357	degrees C/W

* Device mounted on FR-4 PCB 1.5" X 1.6" X 0.06"

N-Channel RF Amplifier

(Continued)

Electrical Characteristics TA= 25 degrees C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
$V_{(BR)GSS}$	Gate-Source Breakdown Voltage	$I_G = -1.0\mu A, V_{DS} = 0$	-25			V
I_{GSS}	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$			-2.0	nA
$V_{GS(off)}$	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_D = 2nA$			-8.0	V
V_{GS}	Gate-Source Voltage	$V_{DS} = 15V, I_D = 200\mu A$	-0.5		-7.5	V
ON CHARACTERISTICS						
I_{DSS}	Zero-Gate Voltage Drain Current	$V_{DS} = 15V, V_{GS} = 0$	2.0		20	mA
g_{fs}	Forward Transconductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1kHz.$	2000		7500	μS
Capacitance						
C_{iss}	Common-Source Input Capacitance	$V_{GS} = 15V, V_{DS} = 0V$ $f = 1 MHz.$			7.0	pf
C_{rss}	Common-Source reverse Transfer Capacitance	$V_{GS} = 15V, V_{DS} = 0V$ $f = 1 MHz.$			3.0	pf

TO-92 Tape and Reel Data

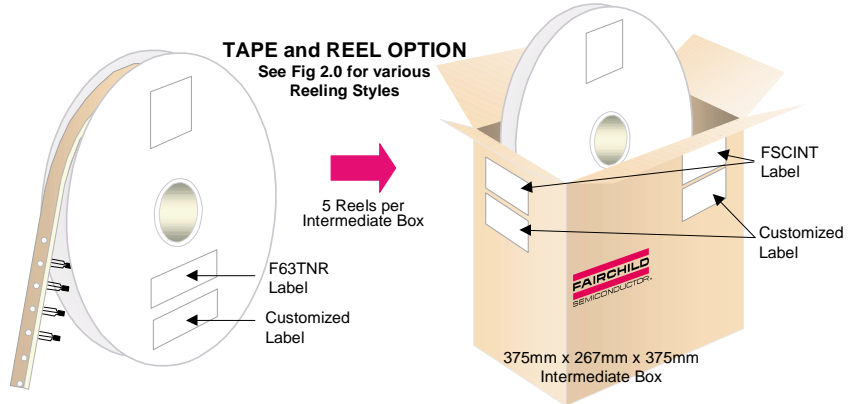


TO-92 Packaging Configuration: Figure 1.0

FSCINT Label sample



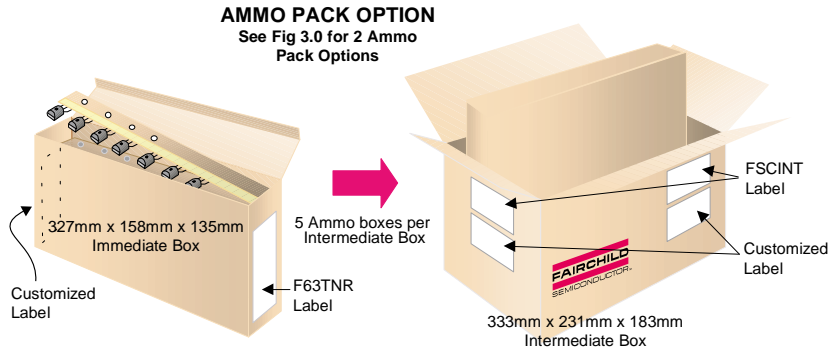
F63TNR Label sample



TO-92 TNR/AMMO PACKING INFORMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
 Reel weight with components = 1.04 kg
 Ammo weight with components = 1.02 kg
 Max quantity per intermediate box = 10,000 units

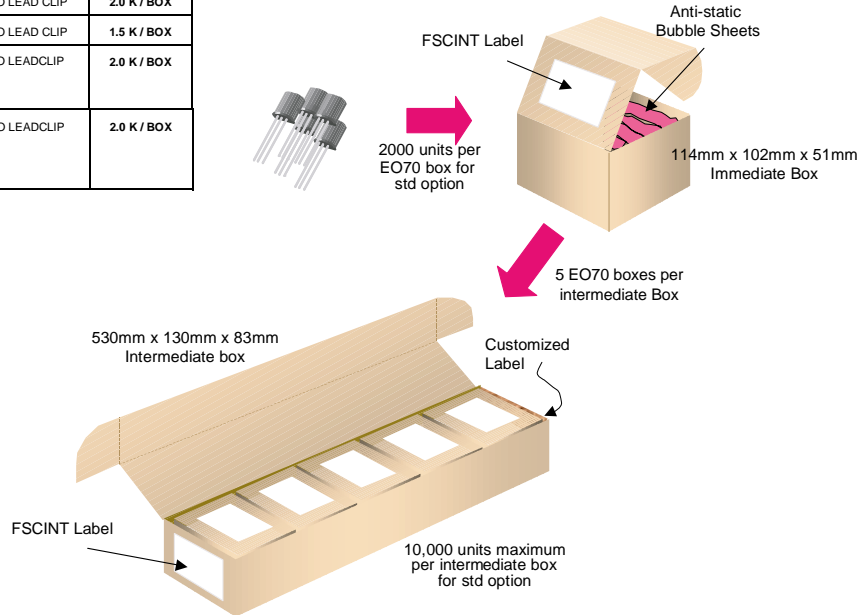


(TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K / BOX
L34Z	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98	NO LEADCLIP	2.0 K / BOX

BULK OPTION

See Bulk Packing Information table

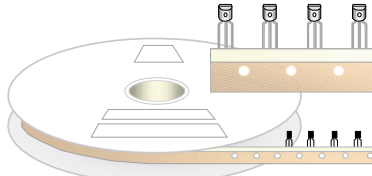


TO-92 Tape and Reel Data, continued

TO-92 Reeling Style

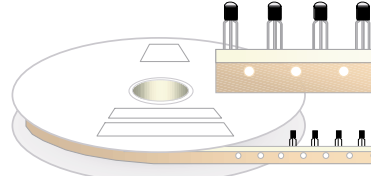
Configuration: Figure 2.0

Machine Option "A" (H)



Style "A", D26Z, D70Z (s/h)

Machine Option "E" (J)

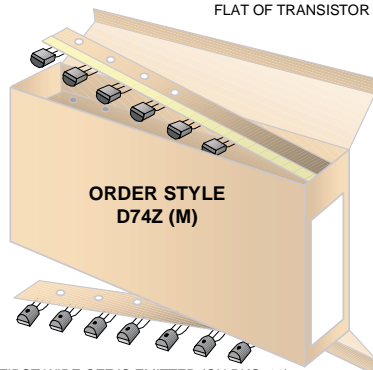


Style "E", D27Z, D71Z (s/h)

TO-92 Radial Ammo Packaging

Configuration: Figure 3.0

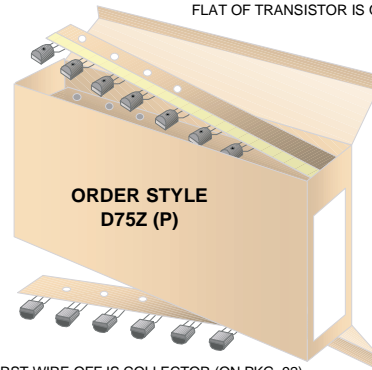
FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



ORDER STYLE
D74Z (M)

FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

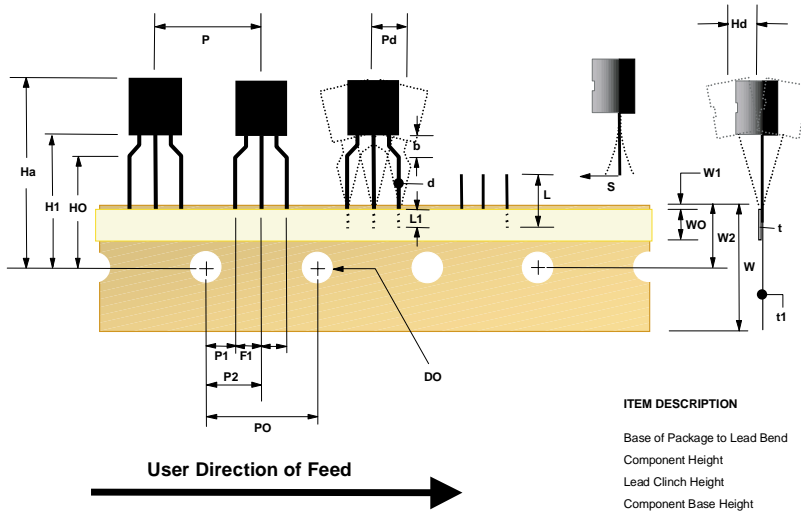


ORDER STYLE
D75Z (P)

FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

TO-92 Tape and Reel Data, continued

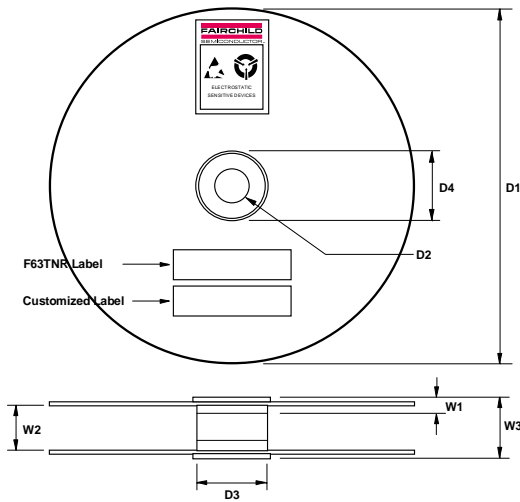
**TO-92 Tape and Reel Taping
Dimension Configuration: Figure 4.0**



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

**TO-92 Reel
Configuration: Figure 5.0**



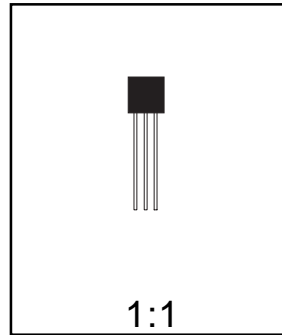
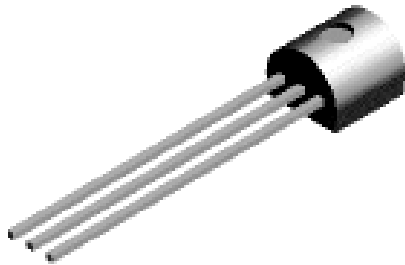
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are in inches

TO-92 Package Dimensions



TO-92 (FS PKG Code 92, 94, 96)



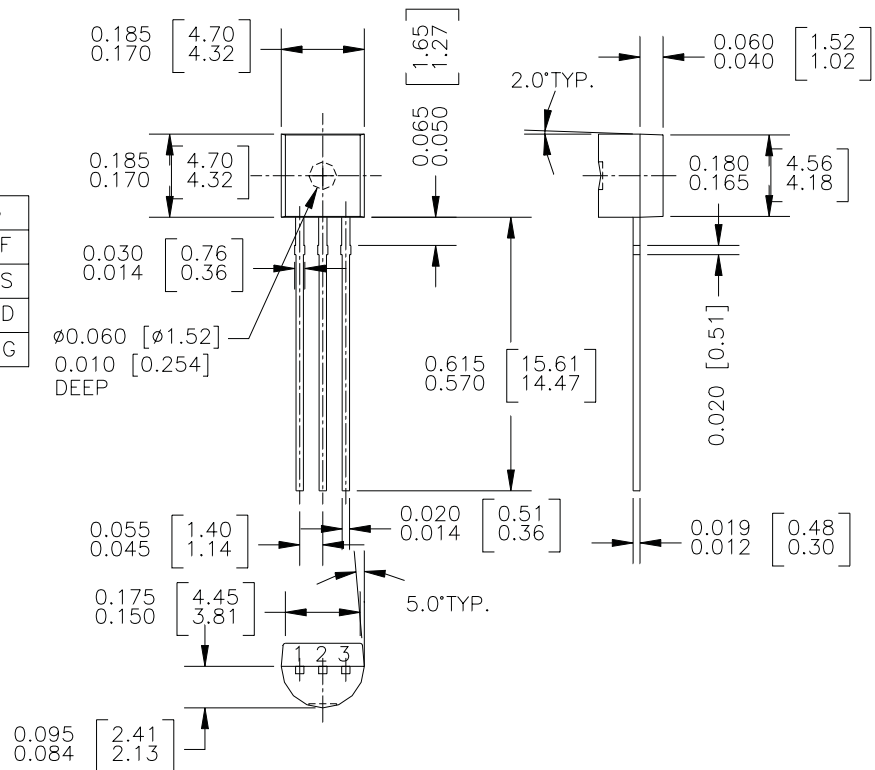
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO-92 (92,94,96)

PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G



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EnSigna™	OPTOLOGIC™	SMART START™	
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